

Multilayer Power Inductor

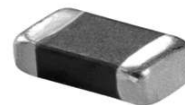
CIG10F Series (1608/ EIA 0603)

APPLICATION

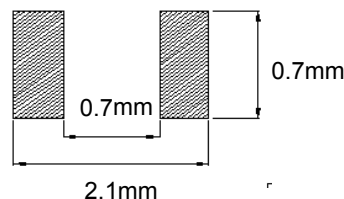
Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

FEATURES

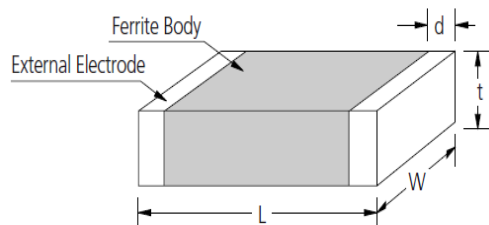
- The smallest multilayer power inductor (1.6mm×0.8mm)
- Much lower Profile than any other series (0.5mm max)
- Low DC resistance
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability



RECOMMENDED LAND PATTERN



DIMENSION



Type	Dimension [mm]			
	L	W	t	d
10	1.6±0.15	0.8±0.15	0.5 max.	0.3+0.2 -0.2

DESCRIPTION

Part no.	Size (inch/mm)	Inductance (uH)@1MHz	DC Resistance(Ω)	Rated Current (A) Max.
CIG10FR47MNC	0603/1608	0.47±20%	0.20±30 %	0.80
CIG10F1R0MNC	0603/1608	1.0±20%	0.30±30 %	0.70
CIG10F1R5MNC	0603/1608	1.5±20%	0.35±30 %	0.60
CIG10F2R2MNC	0603/1608	2.2±20%	0.45±30 %	0.50

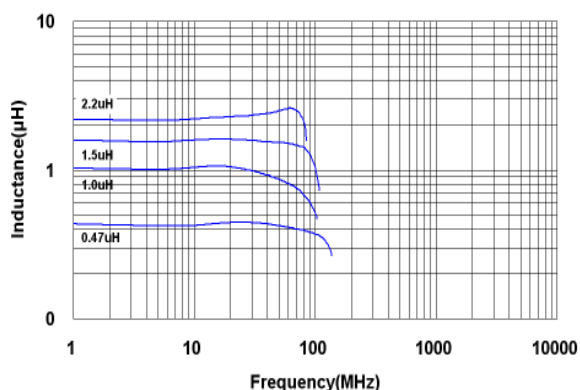
※ Rated Current: DC current value when the self-generation of heat rises to 40℃ (Reference ambient temperature:20℃)

※ Operating temperature range -40 to +85℃

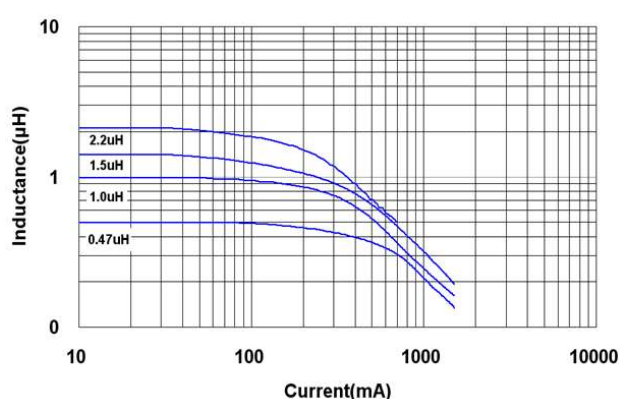
※ Test equipment:Agilent 4291B+16193A

CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



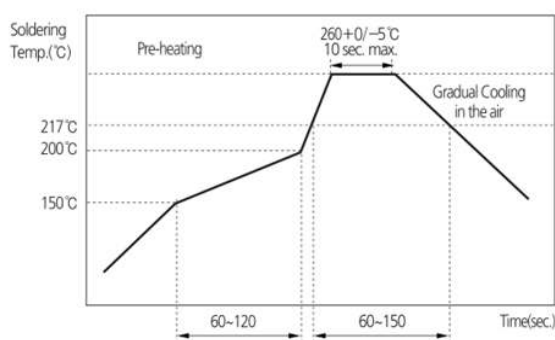
PRODUCT IDENTIFICATION

CI	G	10	F	2R2	M	N	C
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)

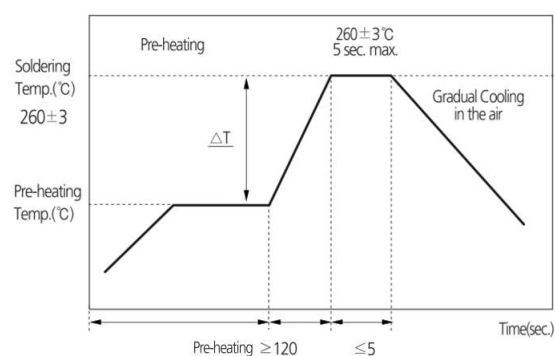
- | | |
|--|---|
| (1) Chip Inductor | (2) Power Inductor |
| (3) Dimension | (4) Product Series (F:Low Profile Type) |
| (5) Inductance (R47:0.47uH, 2R2:2.2uH) | (6) Tolerance (M:±20%) |
| (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard) | |
| (8) Packaging(C:paper tape, E:embossed tape) | |

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	4000